Correction to *J. Electron. Mater.,* 34 (11) (2005), p. 1455.

The first author's name was given incorrectly in the printed version of this paper titled "Effects of Thermoplastic Resin Content of Anisotropic Conductive Films on the Pressure Cooker Test Reliability of Anisotropic Conductive Film Flip-Chip Assembly." The correct names are:

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